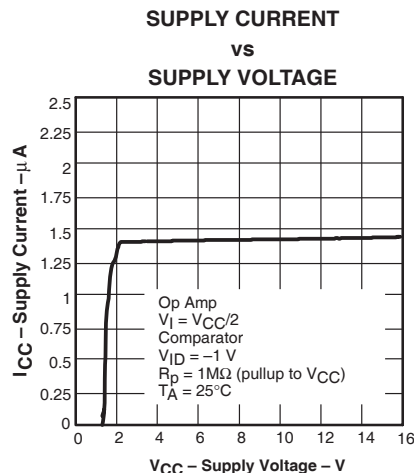
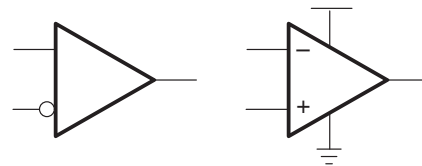


TLV2302, TLV2304

FAMILY OF NANOPOWER OPERATIONAL AMPLIFIERS AND OPEN DRAIN COMPARATORS

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- **Micro-Power Operation . . . 1.4 μ A**
- **Input Common-Mode Range Exceeds the Rails . . . -0.1 V to $V_{CC} + 5$ V**
- **Supply Voltage Range . . . 2.5 V to 16 V**
- **Rail-to-Rail Input/Output (Amplifier)**
- **Reverse Battery Protection Up to 18 V**
- **Gain Bandwidth Product . . . 5.5 kHz (Amplifier)**
- **Open-Drain CMOS Output Stage (Comparator)**
- **Specified Temperature Range**
– $T_A = -40^\circ\text{C}$ to 125°C . . . Industrial Grade
- **Ultrasmall Packaging**
– 8-Pin MSOP (TLV2302)
- **Universal Op-Amp EVM (See the SLOU060 for More Information)**



The TLV230x combines sub-micropower operational amplifier and comparator into a single package that produces excellent micropower signal conditioning with only 1.4 μ A of supply current. This combination gives the designer more board space and reduces part counts in systems that require an operational amplifier and comparator. The low supply current makes it an ideal choice for battery-powered portable applications where quiescent current is the primary concern. Reverse battery protection guards the amplifier from an over-current condition due to improper battery installation. For harsh environments, the inputs can be taken 5 V above the positive supply rail without damage to the device.

The TLV230x's low supply current is coupled with extremely low input bias currents enabling them to be used with mega-ohm resistors making them ideal for portable, long active life, applications. DC accuracy is ensured with a low typical offset voltage as low as 390 μ V, CMRR of 90 dB and minimum open loop gain of 130 V/mV at 2.7 V.

The maximum recommended supply voltage is as high as 16 V and ensured operation down to 2.5 V, with electrical characteristics specified at 2.7 V, 5 V, and 15 V. The 2.5-V operation makes it compatible with Li-Ion battery-powered systems and many micropower microcontrollers available today including TI's MSP430.

All members are available in PDIP and SOIC with the duals (one op-amp and one comparator) in the small MSOP package, and the quads (two operational amplifiers and two comparators) in the TSSOP package.

A SELECTION OF OUTPUT COMPARATORS†

| DEVICE | V_{CC} (V) | V_{IO} (μ V) | I_{CC}/Ch (μ A) | GBW (kHz) | SR (V/ μ s) | t_{PLH} (μ s) | t_{PHL} (μ s) | t_f (μ s) | RAIL-TO-RAIL | OUTPUT STAGE |
|---------|-----------------|------------------------|---------------------------|--------------|--------------------|-------------------------|-------------------------|---------------------|--------------|--------------|
| TLV230x | 2.5 – 16 | 390 | 1.4‡ | 5.5 | 0.0025 | 55 | 30 | 5 | I/O | OD |
| TLV270x | 2.5 – 16 | 390 | 1.4‡ | 5.5 | 0.0025 | 55 | 30 | 5 | I/O | PP |
| TLV240x | 2.5 – 16 | 390 | 880 | 5.5 | 0.0025 | — | — | — | I/O | — |
| TLV224x | 2.5 – 12 | 600 | 1 | 5.5 | 0.002 | — | — | — | I/O | — |
| TLV340x | 2.5 – 16 | 250 | 0.47 | — | — | 55 | 30 | 5 | I | OD |
| TLV370x | 2.5 – 16 | 250 | 0.47 | — | — | 55 | 30 | 5 | I | PP |

† All specifications are typical values measured at 5 V.

‡ I_{CC} is specified as one op-amp and one comparator.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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TLV2302, TLV2304 FAMILY OF NANOPOWER OPERATIONAL AMPLIFIERS AND OPEN DRAIN COMPARATORS

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TLV2302 AVAILABLE OPTIONS

| T _A | V _{IO} max AT 25°C | PACKAGED DEVICES | | | |
|----------------|--------------------------------|-----------------------|----------------|---------|--------------------|
| | | SMALL OUTLINE† (D) | MSOP | | PLASTIC DIP (P) |
| | | | MSOP† (DGK) | SYMBOLS | |
| -40°C to 125°C | 4000 µV | TLV2302ID | TLV2302IDGK | xxTIAQG | TLV2302IP |

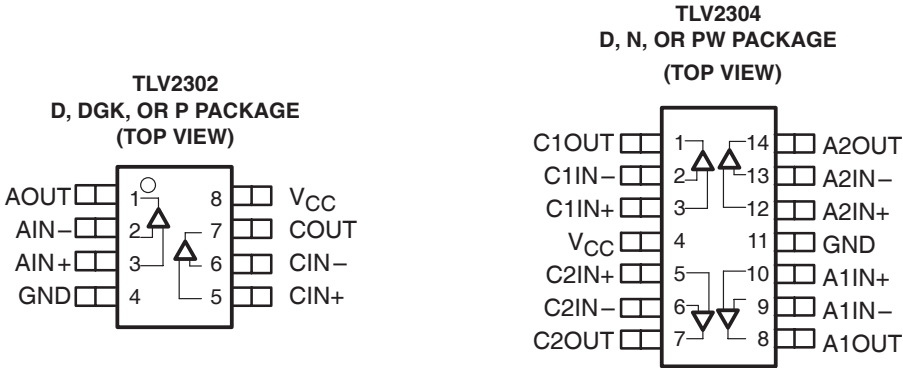
† This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLV2302IDR).

TLV2304 AVAILABLE OPTIONS

| T _A | V _{IO} max AT 25°C | PACKAGED DEVICES | | |
|----------------|--------------------------------|-----------------------|---------------|--------------------|
| | | SMALL OUTLINE† (D) | TSSOP (PW) | PLASTIC DIP (N) |
| -40°C to 125°C | 4000 µV | TLV2304ID | TLV2304IPW | TLV2304IN |

† This package is available taped and reeled. To order this packaging option, add an R suffix to the part number (e.g., TLV2304IDR).

TLV230x PACKAGE PINOUTS



TLV2302, TLV2304
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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| | |
|--------------------------------------------------------------|------------------------------------------------|
| Supply voltage, V_{CC} (see Note 1) | 17 V |
| Differential input voltage, V_{ID} | V_{CC} |
| Input voltage range, V_I (see Notes 1 and 2) | 0 to $V_{CC} + 5$ V |
| Input current range, I_I (any input) | ± 10 mA |
| Output current range, I_O | ± 10 mA |
| Continuous total power dissipation | See Dissipation Rating Table |
| Operating free-air temperature range, T_A : I suffix | -40°C to 125°C |
| Maximum junction temperature, T_J | 150°C |
| Storage temperature range, T_{stg} | -65°C to 150°C |
| Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds | 260°C |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to GND
2. Input voltage range is limited to 20 V max or $V_{CC} + 5$ V, whichever is smaller.

DISSIPATION RATING TABLE

| PACKAGE | θ_{JC} ($^{\circ}\text{C}/\text{W}$) | θ_{JA} ($^{\circ}\text{C}/\text{W}$) | $T_A \leq 25^{\circ}\text{C}$ POWER RATING | $T_A = 125^{\circ}\text{C}$ POWER RATING |
|---------|--------------------------------------------------|--------------------------------------------------|-----------------------------------------------|---------------------------------------------|
| D (8) | 38.3 | 176 | 710 mW | 142 mW |
| D (14) | 26.9 | 122.3 | 1022 mW | 204.4 mW |
| DGK (8) | 54.2 | 259.9 | 481 mW | 96.2 mW |
| N (14) | 32 | 78 | 1600 mW | 320.5 mW |
| P (8) | 41 | 104 | 1200 mW | 240.4 mW |
| PW (14) | 29.3 | 173.6 | 720 mW | 144 mW |

recommended operating conditions

| | | MIN | MAX | UNIT |
|--------------------------------------------|--------------------------|------------|------------|--------------------|
| Supply voltage, V_{CC} | Single supply | 2.5 | 16 | V |
| | Split supply | ± 1.25 | ± 8 | |
| Common-mode input voltage range, V_{ICR} | Amplifier and comparator | -0.1 | $V_{CC}+5$ | V |
| Operating free-air temperature, T_A | | -40 | 125 | $^{\circ}\text{C}$ |

TLV2302, TLV2304

FAMILY OF NANOPOWER OPERATIONAL AMPLIFIERS AND OPEN DRAIN COMPARATORS

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electrical characteristics at recommended operating conditions, $V_{CC} = 2.7, 5 \text{ V}$, and 15 V (unless otherwise noted)

amplifier dc performance

| PARAMETER | TEST CONDITIONS | T_A^\dagger | MIN | TYP | MAX | UNIT |
|---------------------------------------------------------------------|--------------------------------------------------------------------------------------|----------------------------------------|------------|------|------|------------------------------|
| V_{IO} Input offset voltage | $V_O = V_{CC}/2 \text{ V}$, $V_{IC} = V_{CC}/2 \text{ V}$, $R_S = 50 \Omega$ | 25°C | | 390 | 4000 | μV |
| | | Full range | | | 6000 | |
| αV_{IO} Offset voltage draft | | 25°C | | 3 | | $\mu\text{V}/^\circ\text{C}$ |
| CMRR Common-mode rejection ratio | $V_{IC} = 0 \text{ to } V_{CC}$, $R_S = 50 \Omega$ | $V_{CC} = 2.7 \text{ V}$ | 25°C | 55 | 73 | dB |
| | | | Full range | 52 | | |
| | | $V_{CC} = 5 \text{ V}$ | 25°C | 60 | 80 | |
| | | | Full range | 55 | | |
| | | $V_{CC} = 15 \text{ V}$ | 25°C | 66 | 90 | |
| | | | Full range | 60 | | |
| AVD Large-signal differential voltage amplification | $V_{CC} = 2.7 \text{ V}$, $V_{O(pp)} = 1.5 \text{ V}$, $R_L = 500 \text{ k}\Omega$ | 25°C | 130 | 400 | | V/mV |
| | | Full range | 30 | | | |
| | $V_{CC} = 5 \text{ V}$, $V_{O(pp)} = 3 \text{ V}$, $R_L = 500 \text{ k}\Omega$ | 25°C | 300 | 1000 | | |
| | | Full range | 100 | | | |
| | $V_{CC} = 15 \text{ V}$, $V_{O(pp)} = 8 \text{ V}$, $R_L = 500 \text{ k}\Omega$ | 25°C | 400 | 1400 | | |
| | | Full range | 120 | | | |
| PSRR Power supply rejection ratio ($\Delta V_{CC}/\Delta V_{IO}$) | $V_{IC} = V_{CC}/2 \text{ V}$, No load | $V_{CC} = 2.7 \text{ to } 5 \text{ V}$ | 25°C | 90 | 120 | dB |
| | | | Full range | 85 | | |
| | | $V_{CC} = 5 \text{ to } 15 \text{ V}$ | 25°C | 94 | 120 | |
| | | | Full range | 90 | | |

† Full range is -40°C to 125°C .

amplifier and comparator input characteristics

| PARAMETER | TEST CONDITIONS | T_A^\dagger | MIN | TYP | MAX | UNIT |
|------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------|-------------------------|-----|-----|------|------------------|
| I_{IO} Input offset current | $V_O = V_{CC}/2 \text{ V}$, $V_{IC} = V_{CC}/2 \text{ V}$, $R_p = 1 \text{ M}\Omega$ (pullup to V_{CC}), $R_S = 50 \Omega$ | 25°C | | 25 | 250 | pA |
| | | 0 to 70°C | | | 300 | |
| | | Full range | | | 500 | |
| I_{IB} Input bias current | | 25°C | | 100 | 500 | pA |
| | | 0 to 70°C | | | 550 | |
| | | Full range | | | 1000 | |
| $r_{i(d)}$ Differential input resistance | | 25°C | | 300 | | $\text{M}\Omega$ |
| $C_{i(c)}$ Common-mode input capacitance | $f = 100 \text{ kHz}$ | 25°C | | 3 | | pF |

† Full range is -40°C to 125°C .

electrical characteristics at recommended operating conditions, $V_{CC} = 2.7, 5 \text{ V}$, and 15 V (unless otherwise noted) (continued)

amplifier output characteristics

| PARAMETER | TEST CONDITIONS | T_A^\dagger | MIN | TYP | MAX | UNIT |
|------------------------------------|-----------------------------------------------------|--------------------------|------|-----------|-------|---------------|
| V_{OH} High-level output voltage | $V_{IC} = V_{CC}/2$, $I_{OH} = -50 \mu\text{A}$ | $V_{CC} = 2.7 \text{ V}$ | 25°C | 2.55 | 2.65 | V |
| | | Full range | | 2.5 | | |
| | | $V_{CC} = 5 \text{ V}$ | 25°C | 4.85 | 4.95 | |
| | | Full range | | 4.8 | | |
| | | $V_{CC} = 15 \text{ V}$ | 25°C | 14.85 | 14.95 | |
| | | Full range | | 14.8 | | |
| V_{OL} Low-level output voltage | $V_{IC} = V_{CC}/2$, $I_{OL} = 50 \mu\text{A}$ | 25°C | | 180 | 260 | mV |
| | | Full range | | | 300 | |
| I_O Output current | $V_O = 0.5 \text{ V}$ from rail | 25°C | | ± 200 | | μA |

† Full range is -40°C to 125°C .

amplifier dynamic performance

| PARAMETER | TEST CONDITIONS | T_A | MIN | TYP | MAX | UNIT |
|--------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------|-------|-----|------|-----|------------------------------|
| UGBW Unity gain bandwidth | $R_L = 500 \text{ k}\Omega$, $C_L = 100 \text{ pF}$ | 25°C | | 5.5 | | kHz |
| SR Slew rate at unity gain | $V_{O(pp)} = 0.8 \text{ V}$, $R_L = 500 \text{ k}\Omega$, $C_L = 100 \text{ pF}$ | 25°C | | 2.5 | | V/ms |
| ϕ_M Phase margin | $R_L = 500 \text{ k}\Omega$, $C_L = 100 \text{ pF}$ | 25°C | | 60° | | |
| Gain margin | | | | 15 | | dB |
| t_s Settling time | $V_{CC} = 2.7 \text{ or } 5 \text{ V}$, $V_{(STEP)PP} = 1 \text{ V}$, $C_L = 100 \text{ pF}$, $A_V = -1$, $R_L = 100 \text{ k}\Omega$ | 25°C | | 1.84 | | ms |
| | $V_{CC} = 15 \text{ V}$, $V_{(STEP)PP} = 1 \text{ V}$, $C_L = 100 \text{ pF}$, $A_V = -1$, $R_L = 100 \text{ k}\Omega$ | | | 6.1 | | |
| | | | | 32 | | |
| V_n Equivalent input noise voltage | $f = 0.1 \text{ to } 10 \text{ Hz}$ | 25°C | | 5.3 | | μV_{pp} |
| | $f = 100 \text{ Hz}$ | | | 500 | | $\text{nV}/\sqrt{\text{Hz}}$ |
| I_n Equivalent input noise current | $f = 100 \text{ Hz}$ | 25°C | | 8 | | $\text{fA}/\sqrt{\text{Hz}}$ |

supply current

| PARAMETER | TEST CONDITIONS | T_A^\dagger | MIN | TYP | MAX | UNIT |
|---------------------------------------------------------|----------------------------------------------------------------------|------------------------------------------|------|-----|-----|---------------|
| I_{CC} Supply current (one op-amp and one comparator) | $R_p = \text{No pullup}$, Output state high | $V_{CC} = 2.7 \text{ V or } 5 \text{ V}$ | 25°C | 1.4 | | μA |
| | | $V_{CC} = 15 \text{ V}$ | 25°C | 1.4 | 1.7 | |
| | | Full range | | | 2.3 | |
| Reverse supply current | $V_{CC} = -18 \text{ V}$, $V_I = 0 \text{ V}$, $V_O = \text{open}$ | 25°C | | 50 | | nA |

† Full range is -40°C to 125°C .

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electrical characteristics at recommended operating conditions, $V_{CC} = 2.7, 5 \text{ V}$, and 15 V (unless otherwise noted) (continued)

comparator dc performance

| PARAMETER | TEST CONDITION [†] | T_A [†] | MIN | TYP | MAX | UNIT |
|------------------------------------------------------------------------|----------------------------------------------------------------------------------------------|----------------------------------------|------------|------|------|------------------------------|
| V_{IO} Input offset voltage | $V_{IC} = V_{CC}/2$, $R_S = 50 \Omega$, $R_P = 1 \text{ M}\Omega$ (pullup to V_{CC}) | 25°C | | 250 | 5000 | μV |
| | | Full range | | | 7000 | |
| α_{VIO} Offset voltage drift | | 25°C | | 3 | | $\mu\text{V}/^\circ\text{C}$ |
| CMRR Common-mode rejection ratio | $V_{IC} = 0 \text{ to } V_{CC}$, $R_S = 50 \Omega$ | $V_{CC} = 2.7 \text{ V}$ | 25°C | 55 | 72 | dB |
| | | | Full range | 50 | | |
| | | $V_{CC} = 5 \text{ V}$ | 25°C | 60 | 76 | |
| | | | Full range | 55 | | |
| | | $V_{CC} = 15 \text{ V}$ | 25°C | 65 | 88 | |
| | | | Full range | 60 | | |
| A_{VD} Large-signal differential voltage amplification | $R_P = 1 \text{ M}\Omega$ (pullup to V_{CC}) | 25°C | | 1000 | | V/mV |
| PSRR Power supply rejection ratio ($\Delta V_{CC}/\Delta V_{IO}$) | $V_{IC} = V_{CC}/2 \text{ V}$, No load | $V_{CC} = 2.7 \text{ to } 5 \text{ V}$ | 25°C | 75 | 100 | dB |
| | | | Full range | 70 | | |
| | | $V_{CC} = 5 \text{ to } 15 \text{ V}$ | 25°C | 85 | 105 | |
| | | | Full range | 80 | | |

[†] Full range is -40°C to 125°C .

comparator output characteristics

| PARAMETER | TEST CONDITION [†] | T_A [†] | MIN | TYP | MAX | UNIT |
|------------------------------------------------|---------------------------------------------------------------------------|--------------------|-----|-----|-----|------|
| I_{OZ} High-impedance output leakage current | $V_{IC} = V_{CC}/2$, $V_O = V_{CC}$, $V_{ID} = 1 \text{ V}$ | 25°C | | 50 | | pA |
| V_{OL} Low-level output voltage | $V_{IC} = V_{CC}/2$, $I_{OL} = 50 \mu\text{A}$, $V_{ID} = -1 \text{ V}$ | 25°C | | 80 | 200 | mV |
| | | Full range | | | 300 | |

[†] Full range is -40°C to 125°C .

switching characteristics at recommended operating conditions, $V_{CC} = 2.7 \text{ V}$, 5 V , 15 V (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | | T _A | MIN | TYP | MAX | UNIT |
|--------------------|--------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------|-------------------|----------------|-----|-----|-----|------|
| t _(PLH) | Propagation delay time, low-to-high-level output | f = 10 kHz, V _{STEP} = 1 V, C _L = 10 pF, R _p = 1 MΩ (pullup to V _{CC}) | Overdrive = 2 mV | 25°C | | 175 | | μs |
| | | | Overdrive = 10 mV | | | 55 | | |
| | | | Overdrive = 50 mV | | | 25 | | |
| t _(PHL) | Propagation delay time, high-to-low-level output | | Overdrive = 2 mV | 25°C | | 300 | | |
| | | | Overdrive = 10 mV | | | 60 | | |
| | | | Overdrive = 50 mV | | | 30 | | |
| t _f | Fall time | C _L = 10 pF | | 25°C | | 5 | | μs |

NOTE: The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

TYPICAL CHARACTERISTICS

Table of Graphs

| | | | FIGURE |
|--------------------|----------------------------------------------------------------|------------------------------|---------|
| V _{IO} | Input offset voltage | vs Common-mode input voltage | 1, 2 |
| I _{IB} | Input bias current | vs Free-air temperature | 3, 5, 7 |
| | | vs Common-mode input voltage | 4, 6 |
| I _{IO} | Input offset current | vs Free-air temperature | 3, 5, 7 |
| | | vs Common-mode input voltage | 4, 6 |
| I _{CC} | Supply current | vs Supply voltage | 8 |
| | | vs Free-air temperature | 9 |
| Amplifier | | | |
| CMRR | Common-mode rejection ratio | vs Frequency | 10 |
| V _{OH} | High-level output voltage | vs High-level output current | 11, 13 |
| V _{OL} | Low-level output voltage | vs Low-level output current | 12, 14 |
| V _{O(PP)} | Output voltage, peak-to-peak | vs Frequency | 15 |
| PSRR | Power supply rejection ratio | vs Frequency | 16 |
| | Voltage noise over a 10 Second Period | | 17 |
| φ _m | Phase margin | vs Capacitive load | 18 |
| A _{VD} | Differential voltage gain | vs Frequency | 19 |
| | Phase | vs Frequency | 19 |
| | Gain bandwidth product | vs Supply voltage | 20 |
| SR | Slew rate | vs Free-air temperature | 21 |
| | Large signal follower pulse response | | 22 |
| | Small signal follower pulse response | | 23 |
| | Large signal inverting pulse response | | 24 |
| | Small signal inverting pulse response | | 25 |
| Comparator | | | |
| V _{OL} | Low-level output voltage | vs Low-level output current | 26, 27 |
| | Open collector leakage current | vs Free-air temperature | 28 |
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AMPLIFIER AND COMPARATOR TYPICAL CHARACTERISTICS

**INPUT OFFSET VOLTAGE
vs
COMMON-MODE INPUT
VOLTAGE**

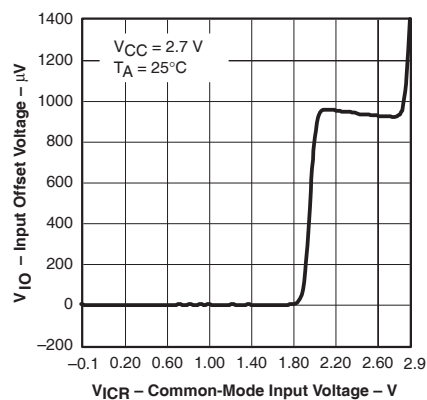


Figure 1

**INPUT OFFSET VOLTAGE
vs
COMMON-MODE INPUT
VOLTAGE**

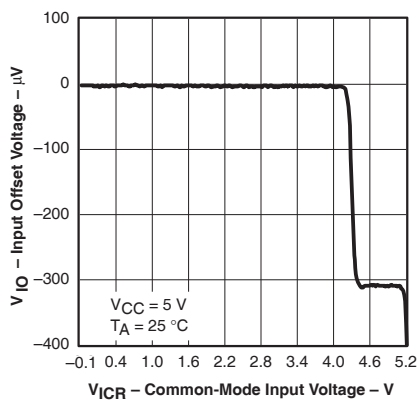


Figure 2

**INPUT BIAS / OFFSET CURRENT
vs
FREE-AIR TEMPERATURE**

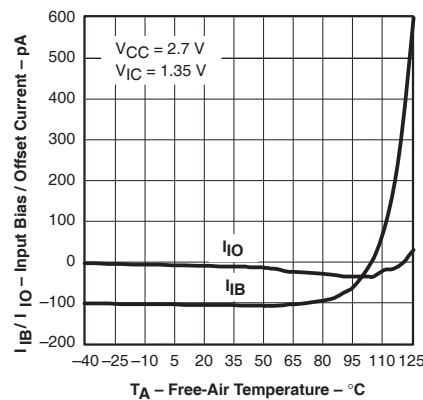


Figure 3

**INPUT BIAS/OFFSET CURRENT
vs
COMMON-MODE INPUT
VOLTAGE**

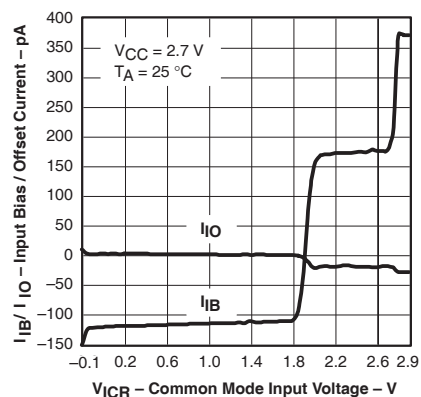


Figure 4

**INPUT BIAS/OFFSET CURRENT
vs
FREE-AIR TEMPERATURE**

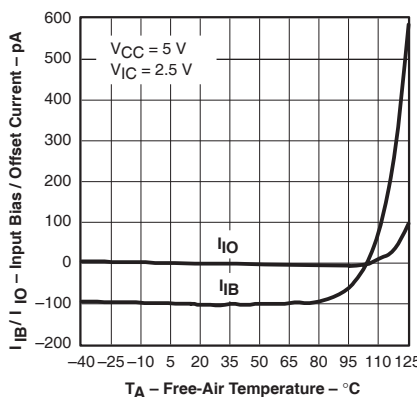


Figure 5

**INPUT BIAS/OFFSET CURRENT
vs
COMMON-MODE INPUT
VOLTAGE**

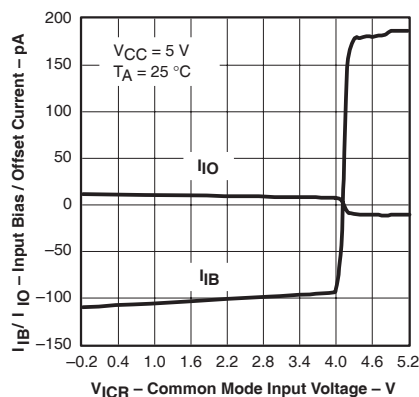


Figure 6

**INPUT BIAS/OFFSET CURRENT
vs
FREE-AIR TEMPERATURE**

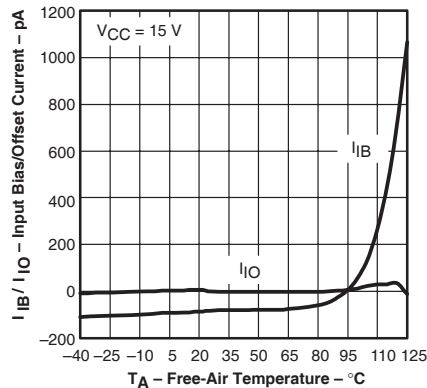


Figure 7

**SUPPLY CURRENT
vs
SUPPLY VOLTAGE**

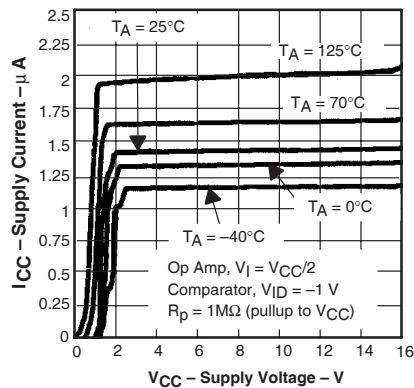


Figure 8

**SUPPLY CURRENT
vs
FREE-AIR TEMPERATURE**

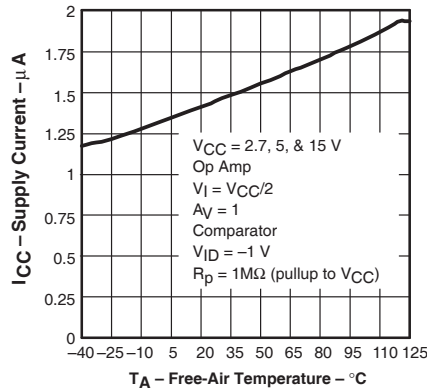


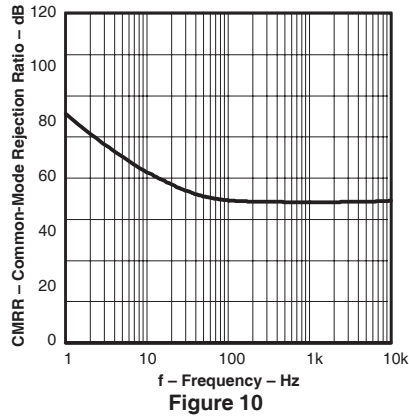
Figure 9



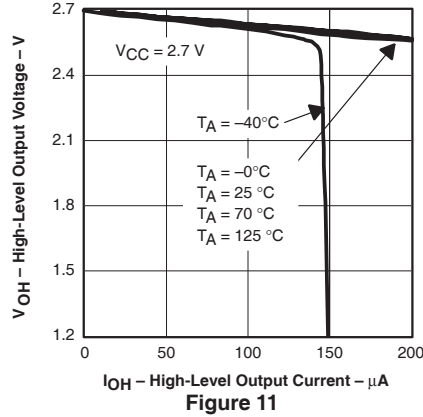
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AMPLIFIER TYPICAL CHARACTERISTICS

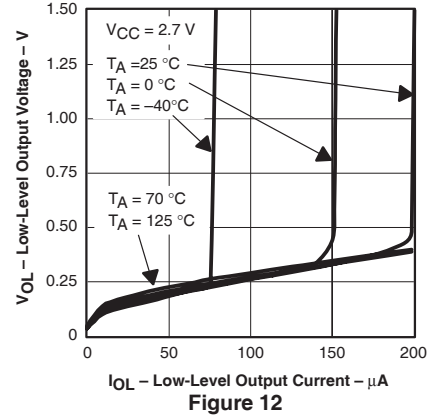
**COMMON-MODE REJECTION RATIO
vs
FREQUENCY**



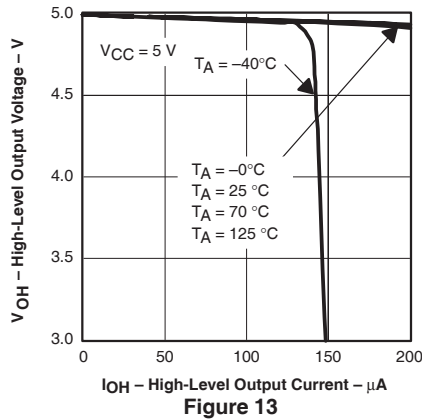
**HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT**



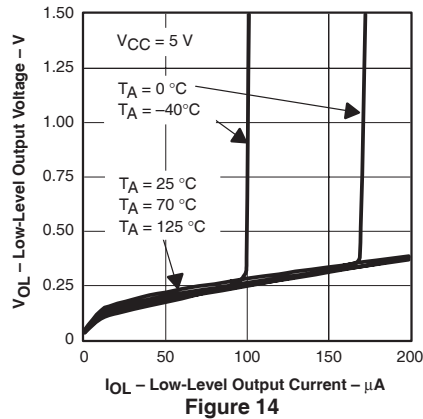
**LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT**



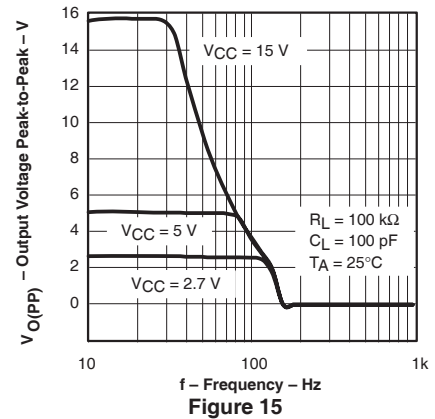
**HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT**



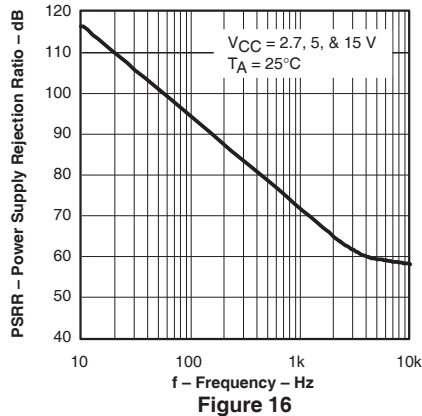
**LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT**



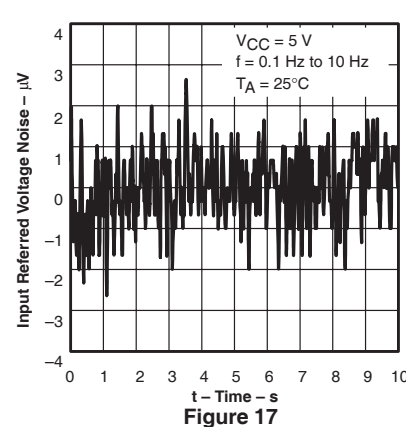
**OUTPUT VOLTAGE
PEAK-TO-PEAK
vs
FREQUENCY**



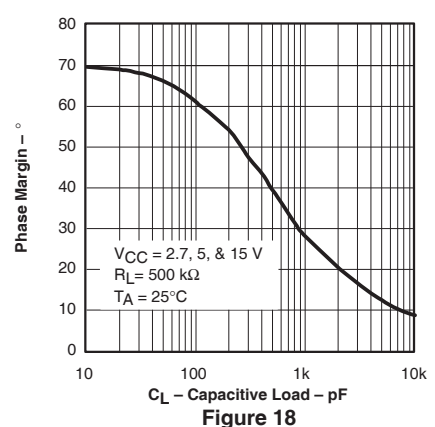
**POWER SUPPLY REJECTION RATIO
vs
FREQUENCY**



**VOLTAGE NOISE
OVER A 10 SECOND PERIOD**



**PHASE MARGIN
vs
CAPACITIVE LOAD**



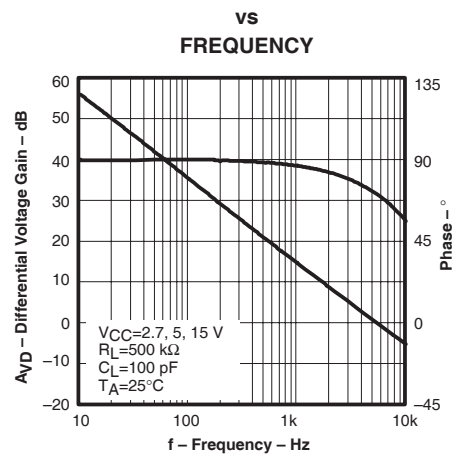
TLV2302, TLV2304

FAMILY OF NANOPOWER OPERATIONAL AMPLIFIERS AND OPEN DRAIN COMPARATORS

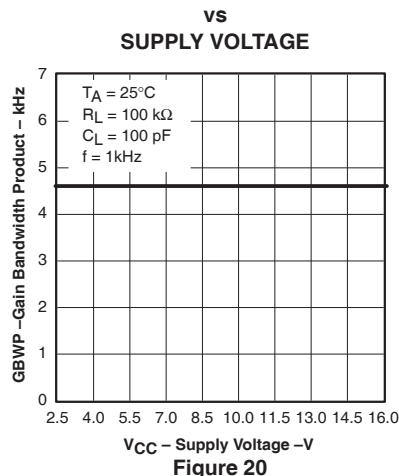
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AMPLIFIER TYPICAL CHARACTERISTICS

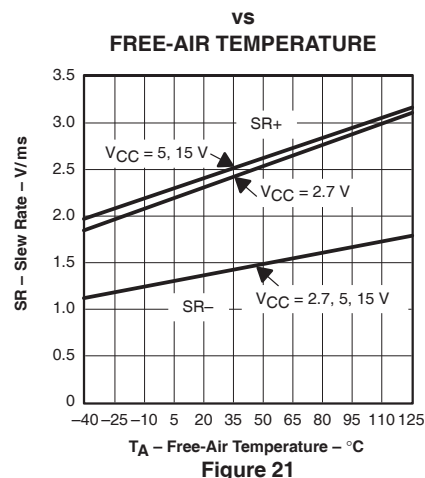
DIFFERENTIAL VOLTAGE GAIN AND PHASE



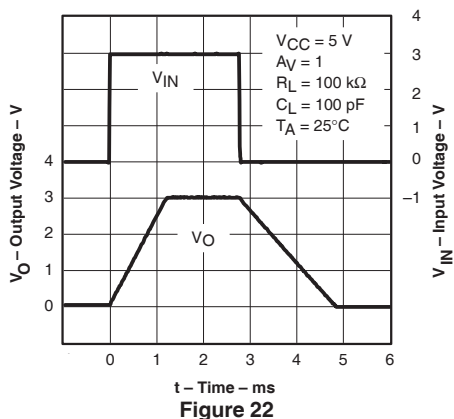
GAIN BANDWIDTH PRODUCT



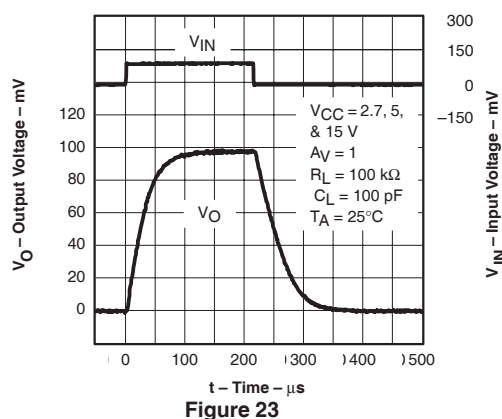
SLEW RATE



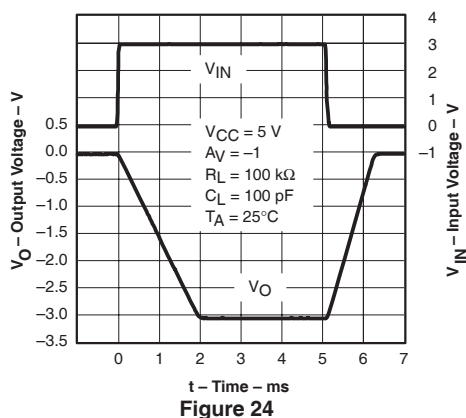
LARGE SIGNAL FOLLOWER PULSE RESPONSE



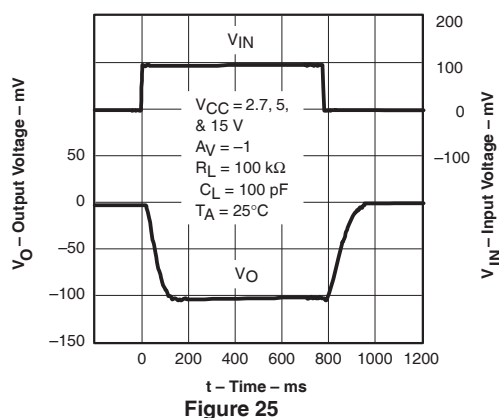
SMALL SIGNAL FOLLOWER PULSE RESPONSE



LARGE SIGNAL INVERTING PULSE RESPONSE



SMALL SIGNAL INVERTING PULSE RESPONSE



COMPARATOR TYPICAL CHARACTERISTICS

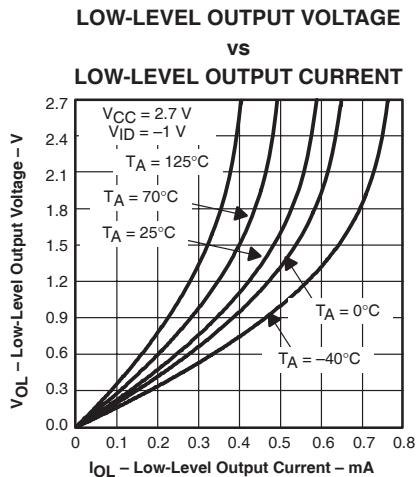


Figure 26

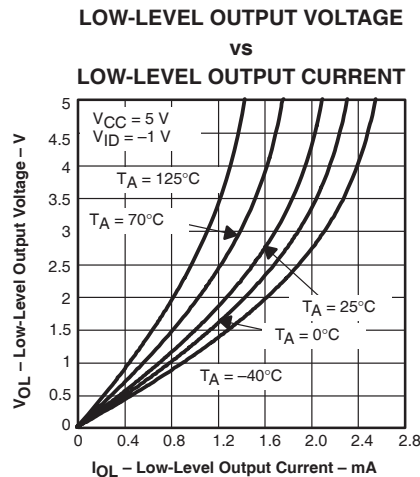


Figure 27

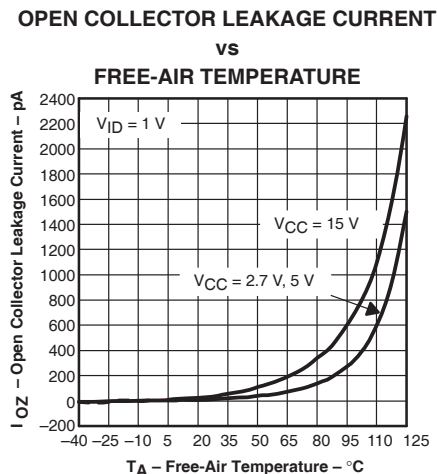


Figure 28

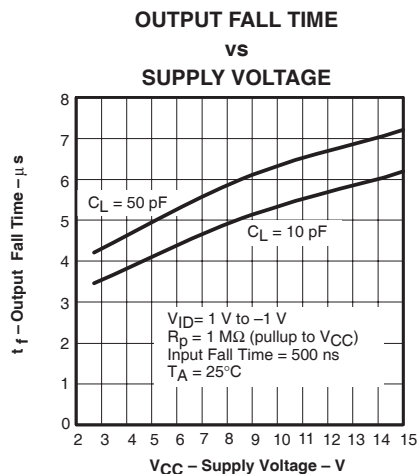


Figure 29

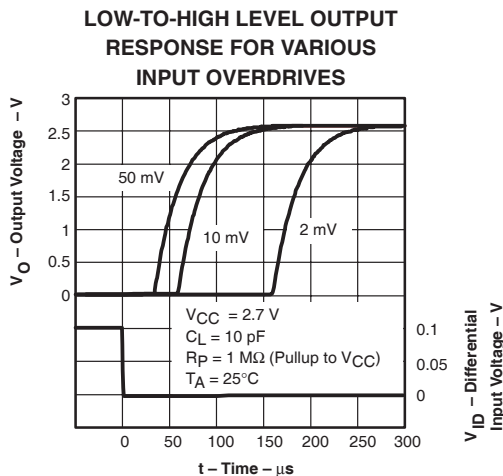


Figure 30

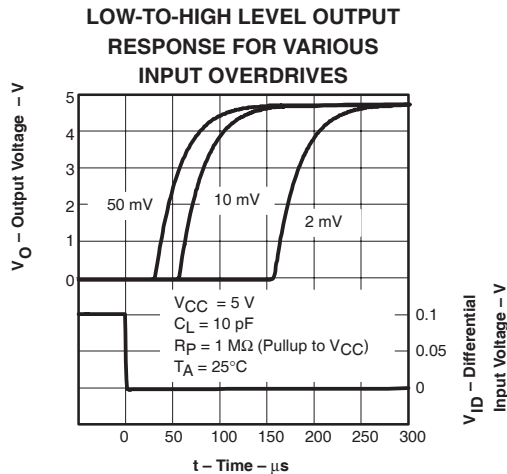


Figure 31

COMPARATOR TYPICAL CHARACTERISTICS

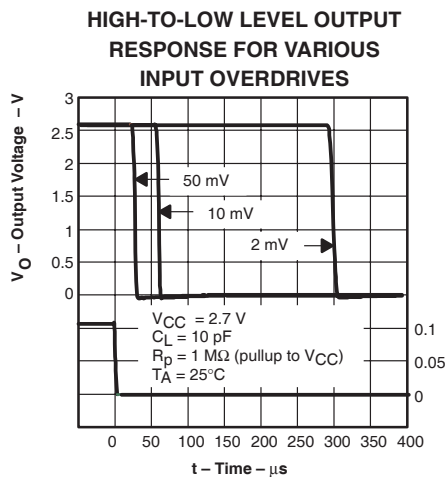


Figure 32

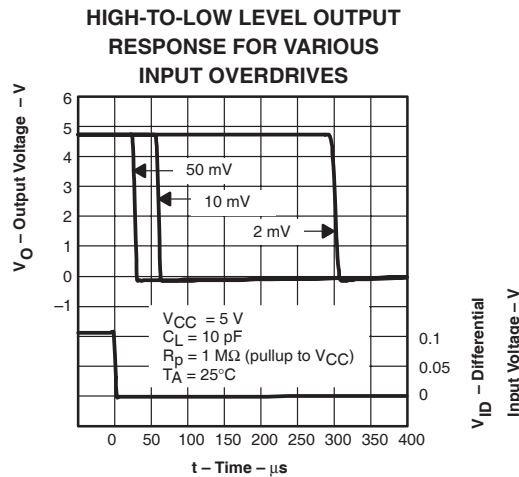


Figure 33

APPLICATION INFORMATION

reverse battery protection

The TLV2302/4 is protected against reverse battery voltage up to 18 V. When subjected to reverse battery condition, the supply current is typically less than 100 nA at 25°C (inputs grounded and outputs open). This current is determined by the leakage of six Schottky diodes and will therefore increase as the ambient temperature increases.

When subjected to reverse battery conditions and negative voltages applied to the inputs or outputs, the input ESD structure will turn on—this current should be limited to less than 10 mA. If the inputs or outputs are referred to ground, rather than midrail, no extra precautions need be taken.

common-mode input range

The TLV2302/4 has rail-rail input and outputs. For common-mode inputs from -0.1 V to $V_{CC} - 0.8$ V a PNP differential pair will provide the gain.

For inputs between $V_{CC} - 0.8$ V and V_{CC} , two NPN emitter followers buffering a second PNP differential pair provide the gain. This special combination of NPN/PNP differential pair enables the inputs to be taken 5 V above the rails; because as the inputs go above V_{CC} , the NPNs switch from functioning as transistors to functioning as diodes. This will lead to an increase in input bias current. The second PNP differential pair continues to function normally as the inputs exceed V_{CC} .

The TLV2302/4 has a negative common-input range that exceeds ground by 100 mV. If the inputs are taken much below this, reduced open loop gain will be observed with the ultimate possibility of phase inversion.

APPLICATION INFORMATION

offset voltage

The output offset voltage, (V_{OO}) is the sum of the input offset voltage (V_{IO}) and both input bias currents (I_{IB}) times the corresponding gains. The following schematic and formula can be used to calculate the output offset voltage.

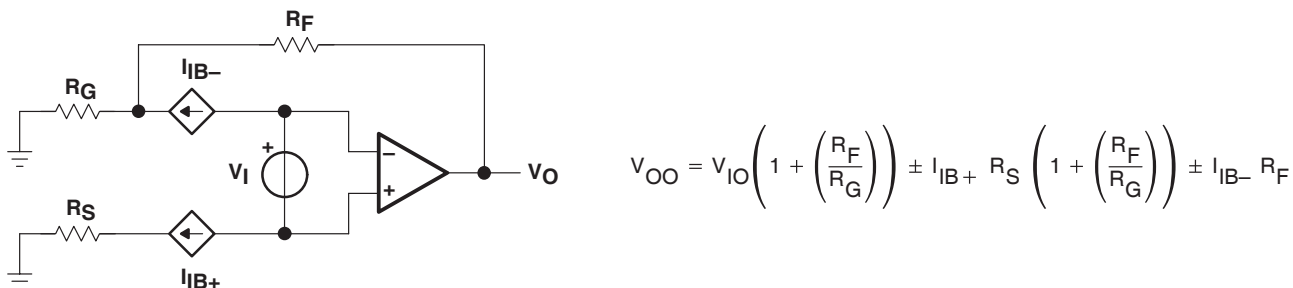


Figure 34. Output Offset Voltage Model

general configurations

When receiving low-level signals, limiting the bandwidth of the incoming signals into the system is often required. The simplest way to accomplish this is to place an RC filter at the noninverting terminal of the amplifier (see Figure 35).

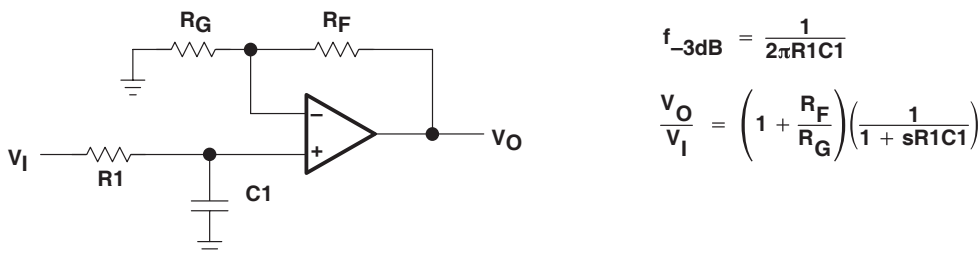


Figure 35. Single-Pole Low-Pass Filter

If even more attenuation is needed, a multiple pole filter is required. The Sallen-Key filter can be used for this task. For best results, the amplifier should have a bandwidth that is 8 to 10 times the filter frequency bandwidth. Failure to do this can result in phase shift of the amplifier.

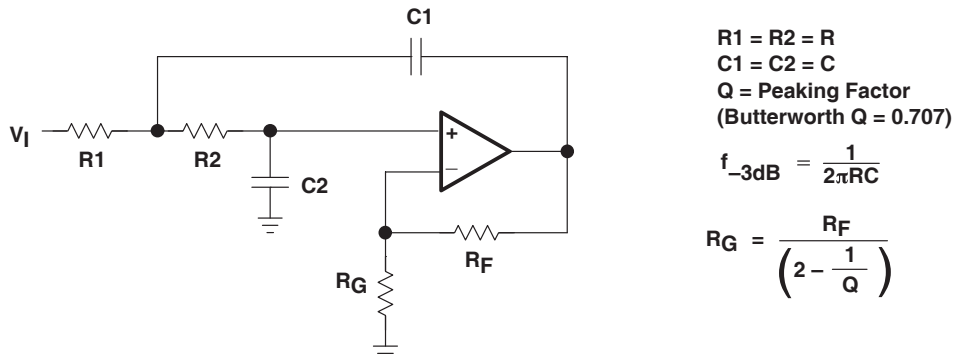


Figure 36. 2-Pole Low-Pass Sallen-Key Filter

APPLICATION INFORMATION

circuit layout considerations

To achieve the levels of high performance of the TLV230x, follow proper printed-circuit board design techniques. A general set of guidelines is given in the following.

- **Ground planes**—It is highly recommended that a ground plane be used on the board to provide all components with a low inductive ground connection. However, in the areas of the amplifier inputs and output, the ground plane can be removed to minimize the stray capacitance.
- **Proper power supply decoupling**—Use a 6.8- μ F tantalum capacitor in parallel with a 0.1- μ F ceramic capacitor on each supply terminal. It may be possible to share the tantalum among several amplifiers depending on the application, but a 0.1- μ F ceramic capacitor should always be used on the supply terminal of every amplifier. In addition, the 0.1- μ F capacitor should be placed as close as possible to the supply terminal. As this distance increases, the inductance in the connecting trace makes the capacitor less effective. The designer should strive for distances of less than 0.1 inches between the device power terminals and the ceramic capacitors.
- **Sockets**—Sockets can be used but are not recommended. The additional lead inductance in the socket pins will often lead to stability problems. Surface-mount packages soldered directly to the printed-circuit board is the best implementation.
- **Short trace runs/compact part placements**—Optimum high performance is achieved when stray series inductance has been minimized. To realize this, the circuit layout should be made as compact as possible, thereby minimizing the length of all trace runs. Particular attention should be paid to the inverting input of the amplifier. Its length should be kept as short as possible. This will help to minimize stray capacitance at the input of the amplifier.
- **Surface-mount passive components**—Using surface-mount passive components is recommended for high performance amplifier circuits for several reasons. First, because of the extremely low lead inductance of surface-mount components, the problem with stray series inductance is greatly reduced. Second, the small size of surface-mount components naturally leads to a more compact layout thereby minimizing both stray inductance and capacitance. If leaded components are used, it is recommended that the lead lengths be kept as short as possible.

APPLICATION INFORMATION

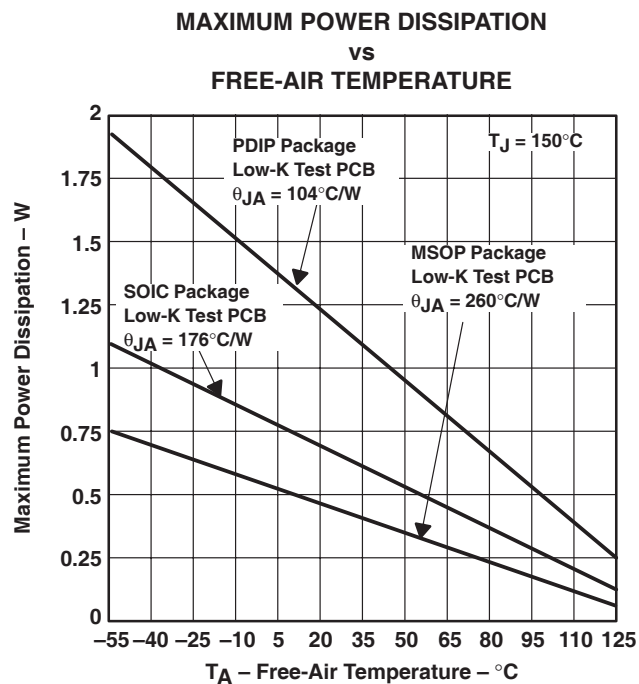
general power dissipation considerations

For a given θ_{JA} , the maximum power dissipation is shown in Figure 37 and is calculated by the following formula:

$$P_D = \left(\frac{T_{MAX} - T_A}{\theta_{JA}} \right)$$

Where:

- P_D = Maximum power dissipation of TLV230x IC (watts)
- T_{MAX} = Absolute maximum junction temperature (150°C)
- T_A = Free-ambient air temperature (°C)
- $\theta_{JA} = \theta_{JC} + \theta_{CA}$
- θ_{JC} = Thermal coefficient from junction to case
- θ_{CA} = Thermal coefficient from case to ambient air (°C/W)



NOTE A: Results are with no air flow and using JEDEC Standard Low-K test PCB.

Figure 37. Maximum Power Dissipation vs Free-Air Temperature

TLV2302, TLV2304

FAMILY OF NANOPOWER OPERATIONAL AMPLIFIERS AND OPEN DRAIN COMPARATORS

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APPLICATION INFORMATION

amplifier macromodel information

Macromodel information provided was derived using Microsim *Parts*™ Release 8, the model generation software used with Microsim *PSpice*™. The Boyle macromodel (see Note 2) and subcircuit in Figure 38 are generated using the TLV230x typical electrical and operating characteristics at $T_A = 25^\circ\text{C}$. Using this information, output simulations of the following key parameters can be generated to a tolerance of 20% (in most cases):

- Maximum positive output voltage swing
- Maximum negative output voltage swing
- Slew rate
- Quiescent power dissipation
- Input bias current
- Open-loop voltage amplification
- Unity-gain frequency
- Common-mode rejection ratio
- Phase margin
- DC output resistance
- AC output resistance
- Short-circuit output current limit

NOTE 3: G. R. Boyle, B. M. Cohn, D. O. Pederson, and J. E. Solomon, "Macromodeling of Integrated Circuit Operational Amplifiers", *IEEE Journal of Solid-State Circuits*, SC-9, 353 (1974).

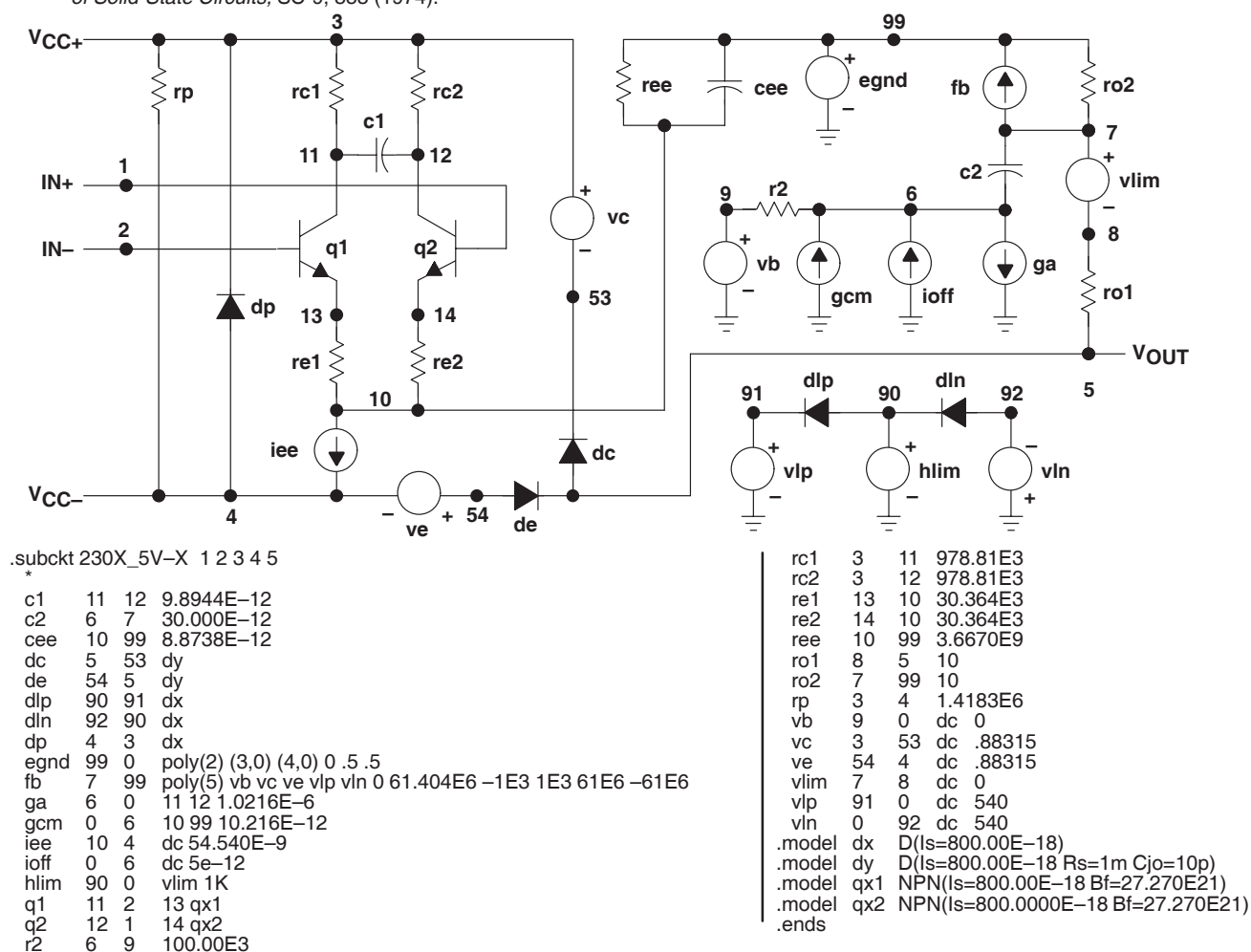


Figure 38. Boyle Macromodels and Subcircuit

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POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/ Ball Finish | MSL Peak Temp ⁽³⁾ | Samples (Requires Login) |
|------------------|-----------------------|--------------|-----------------|------|-------------|----------------------------|----------------------|------------------------------|-----------------------------|
| TLV2302ID | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TLV2302IDG4 | ACTIVE | SOIC | D | 8 | 75 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TLV2302IDGK | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TLV2302IDGKG4 | ACTIVE | VSSOP | DGK | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TLV2302IDGKR | ACTIVE | VSSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TLV2302IDGKRG4 | ACTIVE | VSSOP | DGK | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TLV2302IDR | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TLV2302IDRG4 | ACTIVE | SOIC | D | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TLV2302IP | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | |
| TLV2302IPE4 | ACTIVE | PDIP | P | 8 | 50 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | |
| TLV2304ID | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TLV2304IDG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TLV2304IDR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TLV2304IDRG4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TLV2304IN | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | |
| TLV2304INE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | |
| TLV2304IPWR | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |
| TLV2304IPWRG4 | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

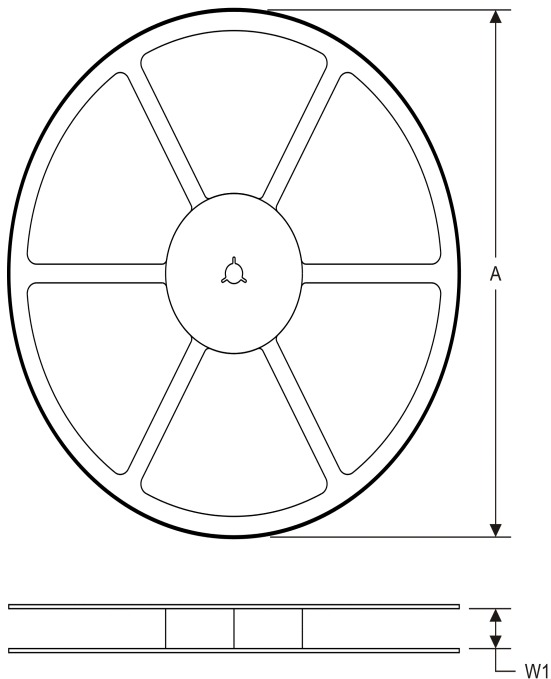
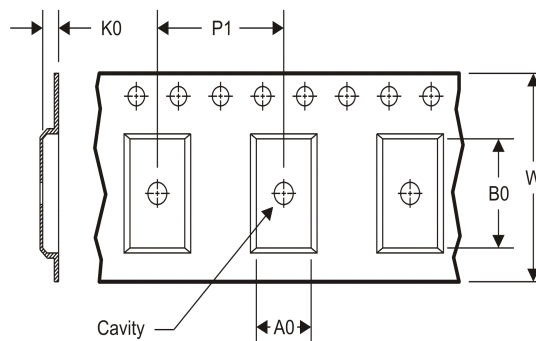
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


| | |
|----|-----------------------------------------------------------|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

TAPE AND REEL INFORMATION

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| TLV2302IDGKR | VSSOP | DGK | 8 | 2500 | 330.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 |
| TLV2302IDR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| TLV2304IDR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| TLV2304IPWR | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| TLV2302IDGKR | VSSOP | DGK | 8 | 2500 | 358.0 | 335.0 | 35.0 |
| TLV2302IDR | SOIC | D | 8 | 2500 | 340.5 | 338.1 | 20.6 |
| TLV2304IDR | SOIC | D | 14 | 2500 | 333.2 | 345.9 | 28.6 |
| TLV2304IPWR | TSSOP | PW | 14 | 2000 | 367.0 | 367.0 | 35.0 |

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